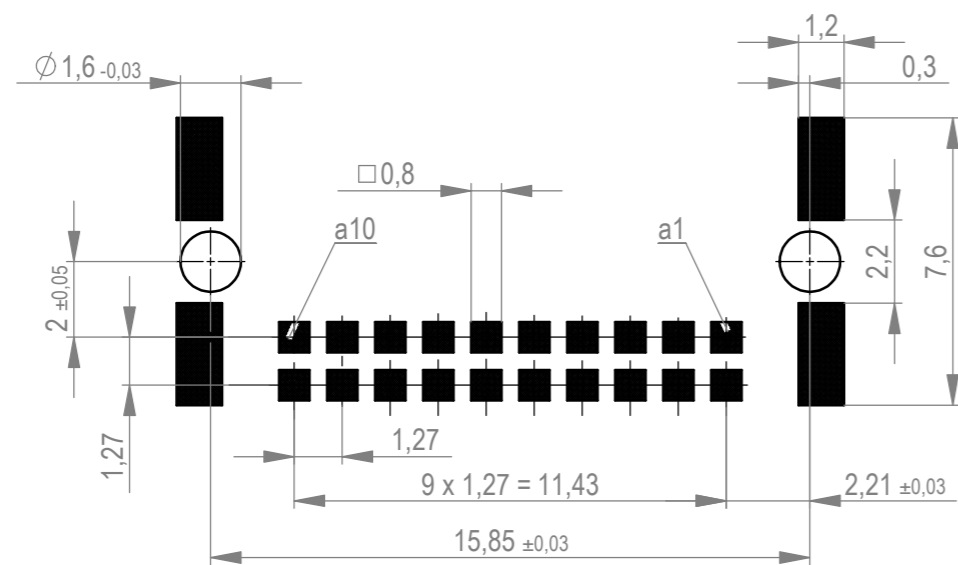
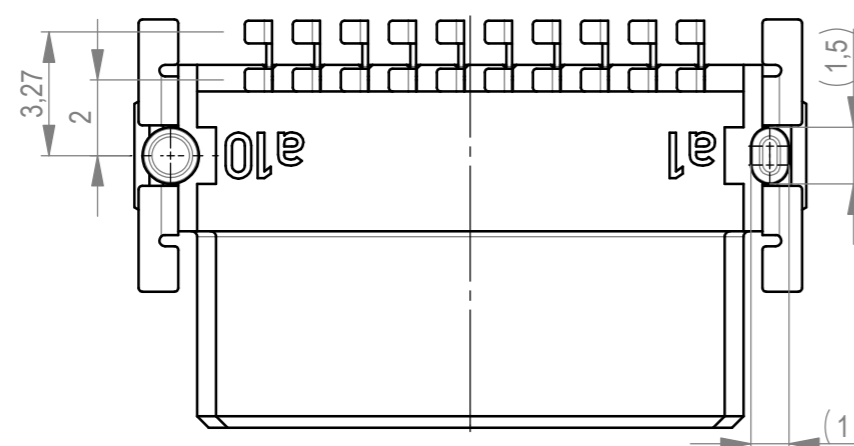
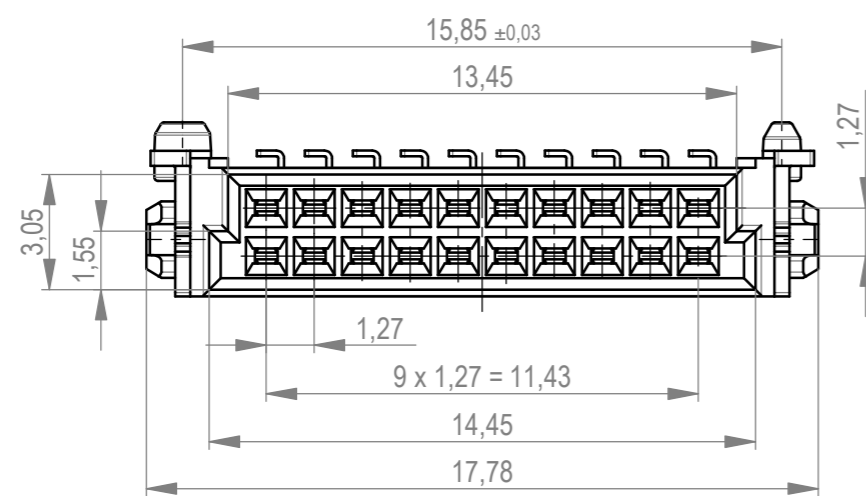
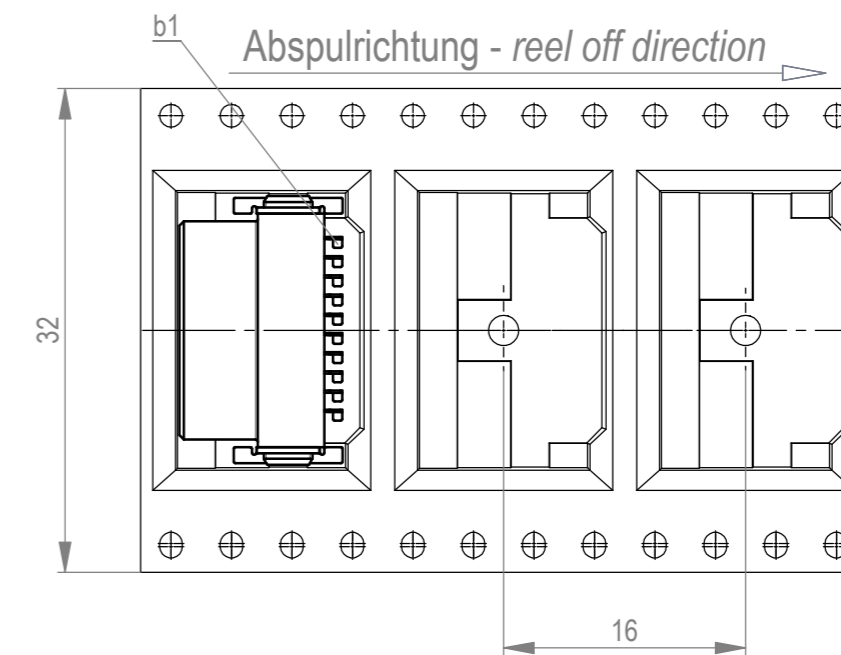
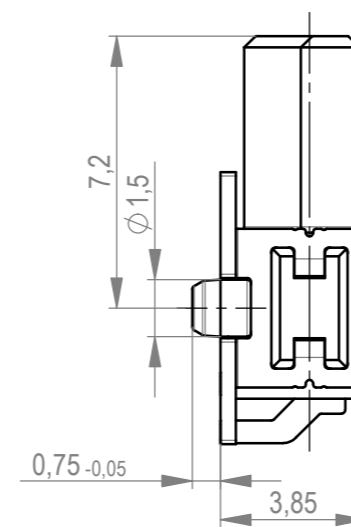
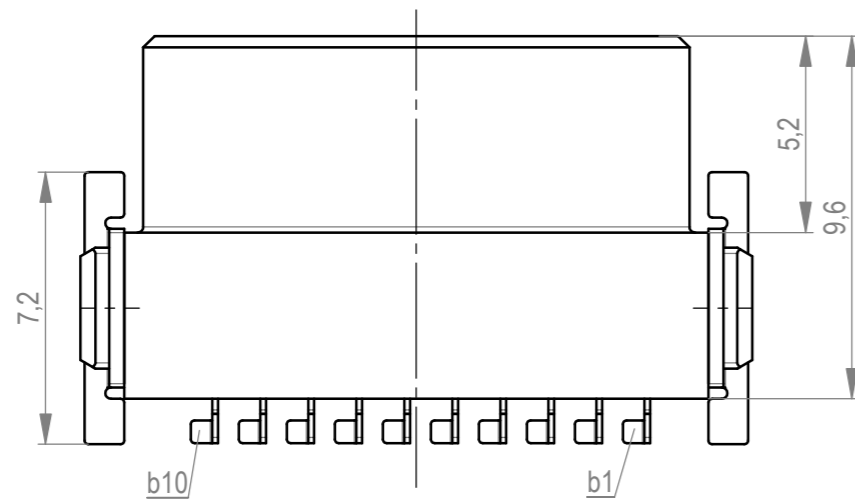
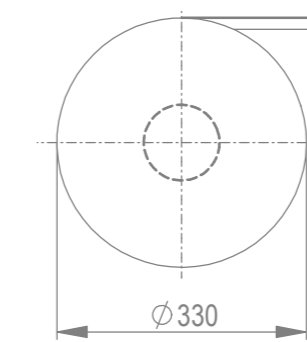


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs



Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

BA7-03 - Standard Bauhöhe

type7-03 - standard assembly height

Die deutsche Version dieser Zeichnung dient nur zur Einweisung der Handlung. Bei Abweichungen vom englischen Original gilt das englische Original. This drawing has been offered for convenience only and may deviate from the original. In case of any deviation the English version shall prevail.

Dimension no.	Tolerances ISO 8015		Scale 5:1 Material
Customer drawing: This Drawing is a controlled Document.	Subject to modification without prior notice. Drawing will not be updated.		Federl. SMC-Q 20-SMD-BA7-03 Female SMC-Q 20-SMD-type7-03
c1 Index		12.05.2023 Date	TE Connectivity
Class			SMCQ

C-354079-E

C
A2